

L Number	Hits	Search Text	DB	Time stamp
-	1290400	silicon adj wafer or semiconductor wafer or wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:30
-	10673	vacuum adj chuck or wafer adj holder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 14:30
-	8861	(silicon adj wafer or semiconductor wafer or wafer) and (vacuum adj chuck or wafer adj holder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 14:30
-	1842	diffusion adj barrier and gold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 14:48
-	30	((silicon adj wafer or semiconductor wafer or wafer) and (vacuum adj chuck or wafer adj holder)) and (diffusion adj barrier and gold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 14:31
-	16964	conductive adj contact	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 14:50
-	50	((silicon adj wafer or semiconductor wafer or wafer) and (vacuum adj chuck or wafer adj holder)) and (conductive adj contact)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:00
-	0	"silicon coated wafer holder" or "silicon coated chuck" or "silicon coated wafer chuck"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:01
-	0	"silicon coated fingers"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:09
-	915386	coated adj chuck or coated wafer adj chuck	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:32
-	811	(diffusion adj barrier and gold) and (coated adj chuck or coated wafer adj chuck)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:10
-	25	(conductive adj contact) and ((diffusion adj barrier and gold) and (coated adj chuck or coated wafer adj chuck))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:18
-	1469	silicon adj coated	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:19
-	14	(vacuum adj chuck or wafer adj holder) and (silicon adj coated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:19

-	566829	bias or biased	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 15:30
-	1290410	silicon adj wafer or semiconductor wafer or wafer or suseptor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 15:44
-	1699	(bias or biased) near (silicon adj wafer or semiconductor wafer or wafer or suseptor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 15:32
-	912136	coated adj chuck or coated wafer adj chuck and ((bias or biased) near (silicon adj wafer or semiconductor wafer or wafer or suseptor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 15:32
-	359	(coated adj chuck or coated wafer adj chuck) and ((bias or biased) near (silicon adj wafer or semiconductor wafer or wafer or suseptor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 15:33
-	1294667	silicon adj wafer or semiconductor wafer or wafer or susceptor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 15:45
-	1719	(bias or biased) near (silicon adj wafer or semiconductor wafer or wafer or susceptor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 15:45
-	359	((coated adj chuck or coated wafer adj chuck) and ((bias or biased) near (silicon adj wafer or semiconductor wafer or wafer or suseptor))) and ((bias or biased) near (silicon adj wafer or semiconductor wafer or wafer or susceptor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 15:59
-	0	"semiconductor coated susceptor"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 16:00
-	7	"silicon coated susceptor"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 16:07
-	5	5324685.URPN.	USPAT	2003/01/20 16:05
-	0	6022587.URPN.	USPAT	2003/01/20 16:05
-	24	("4764394" "4808546" "4933063" "5032202" "5183775" "5196355" "5289010" "5296272" "5304279" "5305221" "5311028" "5342652" "5380682" "5427638" "5436175" "5525159" "5554249" "5554853" "5580429" "5641707" "5653811" "5661043" "5711812" "5854123").PN.	USPAT	2003/01/20 16:05
-	931	"remove native oxide"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 16:08
-	1296714	backside or rear	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 16:08

-	147	"remove native oxide" and (backside or rear)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 16:11
-	2	("6251242").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 16:12
-	1	6217724.URPN.	USPAT	2003/01/20 17:01
-	7	("4579609" "5134301" "5292393" "5653811" "5654043" "6028285" "6120660").PN.	USPAT	2003/01/20 17:03
-	5	silicon adj platen	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 17:10
-	99	"johnsen-rahbek"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 17:13
-	0	"silicon coated electrostatic chuck"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 17:18
-	0	"semiconductor coated electrostatic chuck"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 17:18
-	0	"semiconductor coated chuck"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 17:19
-	0	"semiconductor coated platen"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 17:23
-	6	("5384682" "5663865" "5708557" "5909354" "5969934" "6122159").PN.	USPAT	2003/01/20 17:20
-	0	"semiconductor covered platen"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 17:24
-	0	"semiconductor covered chuck"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 17:25
-	0	"silicon covered chuck"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 17:25
-	0	"silicon covered platen"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 17:25
-	0	"silicon covered sesceptor"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/20 17:25

-	0	"semiconductor covered sesceptor"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 17:25
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